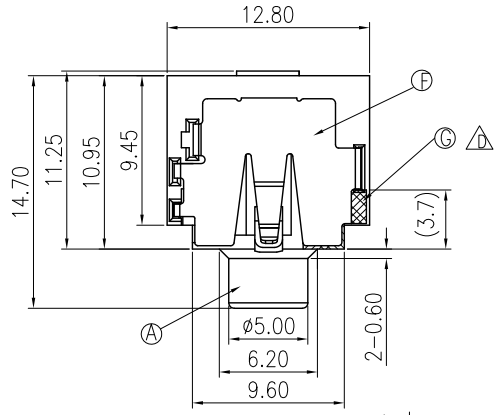
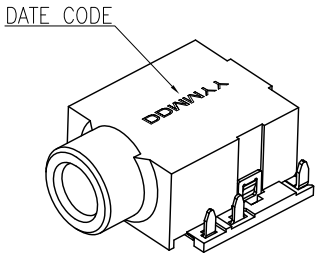
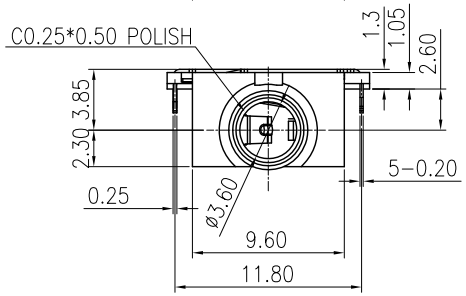
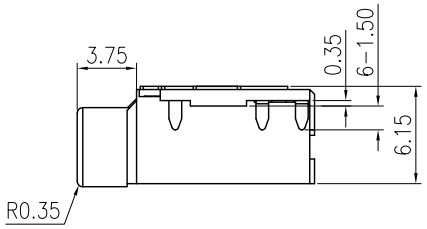
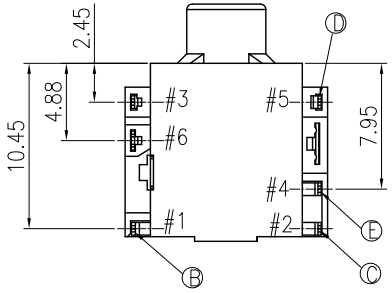
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
C	ECN NO:C110082 Design Chagne	BILLY	2011.04.08
D	ECN NO:C110130 Modify Mylar	BILLY	2011.04.21
E	ECN:C110164Modify Plating specification	LONGJIANG	2011.07.09

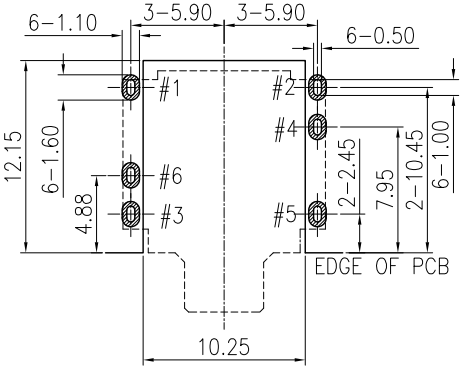






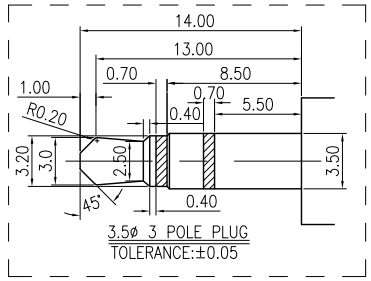


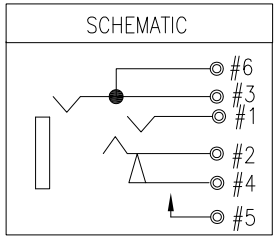




RECOMMENDED P.C.B. LAYOUT T=1.20

TOP VIEW (TOLRANCE: ±0.05)





SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:
   - 1-1. RATING:12V AC, 1A DC.
   - 1-2. CONTACT RESISTANCE: 50m Ω MAX.
   - 1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
   - 1-4. INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
2. MECHANICAL CHARACTERISTICS:
   - 2-1. INSERTION FORCE : 0.4~3.0 KGF
   - 2-2. WITHDRAWAL FORCE : 0.3~2.0 KGF
3. LIFE TEST: 5,000 CYCLES MIN.
4. OTHER GENERAL SPEC. TO REFER "2SJ2311 SERIES SPEC".
5. TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ◎
7. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
8. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
9. PACKAGING: TAPE & REEL.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
G	MYLAR	1	3M 347 0.05T	
F	EARTH	1	COPPER ALLOY 0.20T	NI PLATING
E	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	Gold flash on Contact area and Solder tail, all over Nickel Plated△E
D	MAKE TERMINAL	1	COPPER ALLOY 0.20T	GOLD FLASH
C	RING	1	COPPER ALLOY 0.20T	Gold flash on Contact area and Solder tail, all over Nickel Plated△E
B	TIP	1	COPPER ALLOY 0.25T	
A	BODY	1	PA10T+30%GF UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: ANGLES:
X :±0.5 X :±2°
X.X :±0.3 X.X :±1°
X.XX :±0.2

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK			
DWN	LONGJIANG 2011.7.12	PART NO. 2SJ2311-000211F		
CHKD	ZJZ 2011.7.12	SCALE B:1	UNIT: mm	
APVD	LAIO 2011.7.12	SIZE: A3	SHEET: 1OF1	REV: E

CUSTOMER COPY

文件編號 RD-06-043-A